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 TI Lead-free **tin** alloy **solders** for electric circuits  
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 PA Matsushita Electric Ind Co Ltd, Japan  
 SO Jpn. Kokai Tokkyo Koho, 5 pp.  
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PI	JP 08206874	A2	19960813	JP 1995-18048	19950206
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PRAI	JP 1995-18048	A3	19950206		

AB The **Sn** alloy **solders** contain (1) Ag 0.1-20, **Bi** 0.1-25 and/or In 0.1-20, and optionally **Cu** 0.1-3.0 and/or Zn 0.1-15%, or (2) Sb 0.1-20, **Bi** 0.1-30 and/or In 0.1-20, and optionally **Cu** 0.1-3.0 and/or Zn 0.1-15%. The **solders** have low m.p., high strength and wettability, and are suitable for **soldering** electronic parts.